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(54) **ACOUSTIC WAVE DEVICE**

(71) Applicant: **Murata Manufacturing Co., Ltd.**, Nagaokakyo-shi (JP)

(72) Inventor: **Kazumasa HARUTA**, Nagaokakyo-shi (JP)

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(57) **ABSTRACT**

An acoustic wave device includes a support, a piezoelectric layer having anisotropy of a coefficient of linear expansion, and including first and second main surfaces, and first and second electrodes on the first and second main surfaces of the piezoelectric layer. The support includes a hollow portion. At least a portion of the first and second electrodes overlaps the hollow portion. A heat dissipation structure including the support is provided on the first main surface side of the piezoelectric layer. One of a first and second region includes a high heat dissipation region. Each of the first and second electrodes includes an electrode layer having a higher coefficient of linear expansion than a maximum coefficient of linear expansion of the piezoelectric layer.